BRIEF ABOUT

1. PROF. (Dr.) SHIV DAYAL PANDEY

Vice Chancellor,

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2. EDUCATIONAL QUALIFICATION:

- B.Tech.(Mechanical Engineering), M.Tech.(IIT, BHU, Varanasi), Ph.D. (MNNIT, Allahabad), IAENG(U.K).
- Four times GATE qualified.

ACHIEVEMENTS:

- Worked as a Vice Chancellor, Madhyanchal Professional University, Bhopal, M.P.
- Worked as a Dean (UIT) & PVC (Pro.VC) at Uttaranchal University, Dehradun, UK (NAAC A+ Accredited).
- Worked as a Provost (Pro.VC) at Dr. K.N.Modi University, Jaipur, Rajasthan (NAAC Accredited).
- Worked as a Pro.VC and Dean (SET) at Om Sterling Global University, Hisar, Haryana.
- Worked as a Director at Dr. K.N.Modi Foundation, Modinagar, Delhi-NCR (NBA Accredited).
- Worked as a Director (Engineering) at K.N.I.P.S.S., Sultanpur, U.P.
- Expert in NAAC, NIRF, and NBA accreditations. Successfully completed NAAC accreditation at Uttaranchal University, Dehradun, and earned an **A+ Grade**. Also successfully completed NBA accreditation at Dr. KMIET, Modinagar, securing provisional accreditation **for three years**.
- Visiting Professor at IITs, NITs, and other esteemed universities in India and abroad.
- Provided consultancy to PHE industries in India and abroad, including countries like Canada, the USA (California), Switzerland, and Germany.
- Supervised 7 Ph.D. candidates (completed), with 5 currently under supervision; also guided 25 M.Tech. and 80 B.Tech. students.

- Organized and coordinated 35+ Faculty Development Programs (FDPs), Management Development Programs (MDPs), and conferences/seminars in collaboration with institutions like IIT BHU, IIT Roorkee, NIIT Chandigarh, and organizations such as AICTE, DST, and DRDO.
- Member of several professional societies and organizations, including the Academic Council of UPTU, Lucknow; IEEE; IEI (India); Elsevier, etc. Also served as an AICTE Expert Committee Member (ID: 1-2170902331).
- Editor and Editor-in-Chief of the *International Journal of Engineering and Science* (ISSN: 2348-3302), and editor of seven engineering books and souvenirs.
- Successfully completed fifteen sponsored research and consultancy projects as Principal Investigator, with funding of ₹15L, ₹10L, ₹18L, ₹20L and ₹30L respectively from reputed industries and organizations.
- Reviewer for reputed journals published by Elsevier, Taylor & Francis, Wiley, Springer, IEEE, and Hindawi.
- Extensive exposure to the functioning of key and apex university bodies such as the Governing Body, Board of Management, Academic Council, Finance Committee, Research Board, Faculty Board, and Board of Studies.
- Hands-on experience in designing schemes and syllabi for undergraduate and postgraduate programs as Dean, Chairman of the Board of Studies (BOS), and BOS member.
- Experienced in examination management and providing technical consultancy.

b. Academic & Industrial Experience:

- 27 years of Glorious Teaching experience with Administration experience.
- 5 years Industry experience in HCC Mumbai.
- 7 years' research experience from IIT, BHU, Varanasi and MNNIT, Allahabad.

c. Details of Patents & Paper Published:

- PATENTS: 28 (National & International) 17 patents in field of PHE and IoT etc.
- 108+ research papers published in International and National Journals, Conferences & Seminar.
- 680+ citations, 25 h–index (Scopus Result).

d. Awards and Honors:

- IIT, BHU, Varanasi awarded Honors degree in M.Tech. program.
- Best Director award by CEE, New Delhi in association with UPTU, Lucknow on 6th Sep.2014.

e. Editorships:

- Associate Editor, Journal of Thermal Analysis and Calorimetry (Springer).
- Members of Editorial Board, International Journal of Experimental Thermal and Fluid Science (Elsevier).
- Members of Editorial Board, Journal of Mechanical Engineering research.
- Members of Editorial Board, the open Mechanical Engineering Journal.